plerow[™] APM2350-P29





Features

- · S₂₁ = 29.8 dB @ 2300 MHz
 - = 28.2 dB @ 2400 MHz
- · NF of 2.1 dB over Frequency
- · Unconditionally Stable
- Single 5V Supply
- · High OIP3 @ Low Current

Description

The plerow[™] APM-Series is an internally matched amplifier mini-module for such application band in SMD package with the output P1dB of 29 dBm. It is compactly designed for low current consumption and high OIP3. Integrating all the components for biasing and matching within the module enhances production yield and throughput as well. It passes through the stringent DC, RF, and reliability tests. Not sample test but 100% quality control test is made before packing.



Specifications (in Production)

Typ. @ T = 25°C, V_s = 5 V, Freq. = 2350 MHz, $Z_{o.sys}$ = 50 ohm Specifications Parameter Unit Min Тур Max **Frequency Range** MHz 2300 2400 Gain dB 28 29 Gain Flatness dB ± 0.8 ± 0.9 Noise Figure dB 2.1 2.2 Output IP3 (1) dBm 44 47 S11 / S22 (2) dB -18 / -10 Output P1dB dBm 28 29 Switching Time (3) μsec _ 1 Supply Current mΑ 460 500 Supply Voltage V 5 Impedance Ω 50 Max. RF Input Power dBm C.W 23 ~ 25 (before fail) Package Type & Size mm Surface Mount Type, 13Wx13Lx3.8H



2-stage Single Type

More Information

Website: www.asb.co.kr E-mail: sales@asb.co.kr

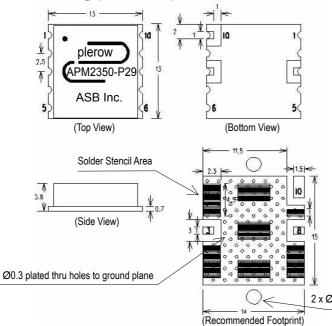
Tel: (82) 42-528-7223 Fax: (82) 42-528-7222

ASB Inc., 4th Fl. Venture Town Bldg., 367-17 Goijeong-Dong, Seo-Gu, Daejon 302-716, Korea

Operating temperature is -40°C to +85°C.

1) OIP3 is measured with two tones at an output power of 15 dBm / tone separated by 1 MHz.
2) S11/S22 (max) is the worst value within the frequency band.
3) Switching time means the time that takes for output power to get stabilized to its final level after switching DC voltage from 0 V to V_S.

Outline Drawing (Unit: mm)



Pin Number	Function		
3	RF In		
8	RF Out		
10	Vs		
Others	Ground		

Note: 1. The number and size of ground via holes in a circuit board is critical for thermal RF grounding considerations.

2. We recommend that the ground via holes be placed on the bottom of all ground pins for better RF and thermal performance, as shown in the drawing at the left side.

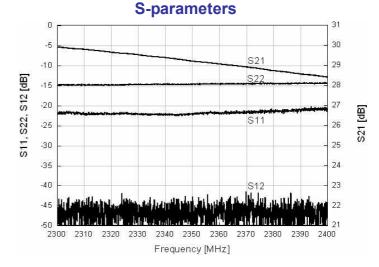
2 x Ø2.0 plated thru holes to screw on heat sinker



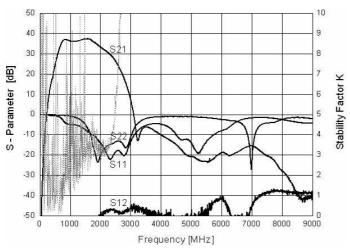
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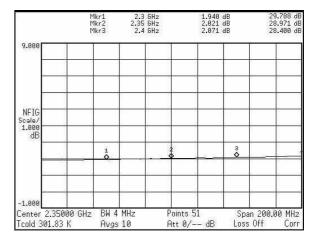
Low Noise & High OIP3 Medium Power Amplifier Module





Noise Figure

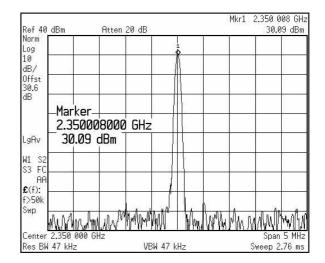




OIP3

Lenter 2.350	000000 GHz		
Ref 16.7 dBm	#Atten 46 dB _♠	M	kr1 2.349 500 G 14.925 dB
#Samp			
10 dB/			
0ffst			
dB	have been been been been been been been be	man hanne	
Center 2.350 000 GH Res BW 47 kHz	lz VBW 47	' kHz	Span 5 MH Sweep 8.64 m
TOI (Worst Cas	e) 2.351 GHz	47.72 dBm	
TOI lower TOI upper	2.349 GHz 2.351 GHz	48.18 dBm 47.72 dBm	

P1dB



Stability Factor (K)

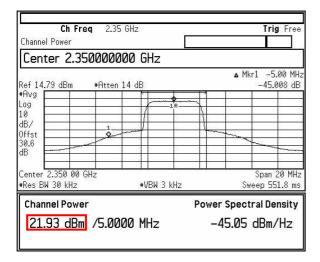


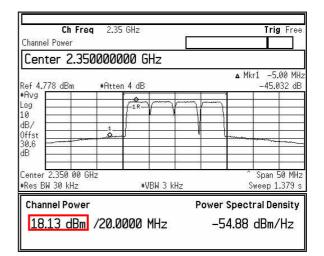
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Low Noise & High OIP3 Medium Power Amplifier Module

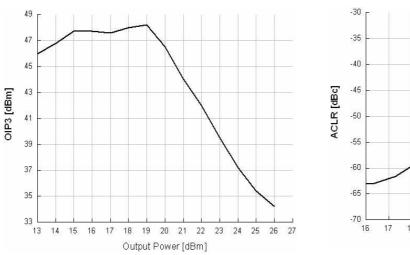
Output Channel Power

(@ ACLR=-45dBc, +/-5MHz Offset)

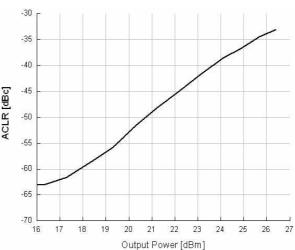




OIP3 vs Output Power (@ 1MHz offset, 1-tone power)



ACLR vs Channel Power

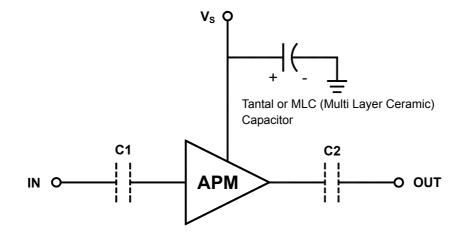


** Test Source : Agilent E4433B (3GPP W-CDMA Test Model-1 64DPCH)



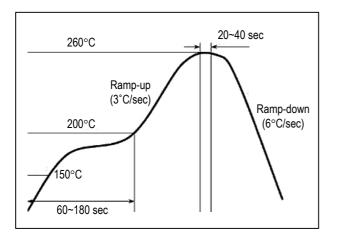
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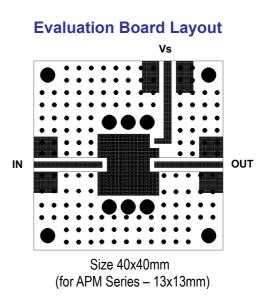
Application Circuit



- The tantal or MLC (Multi Layer Ceramic) capacitor is optional and for bypassing the AC noise introduced from the DC supply. The capacitance value may be determined by customer's DC supply status. The capacitor should be placed as close as possible to V_s pin and be connected directly to the ground plane for the best electrical performance.
- 2) DC blocking capacitors are always necessarily placed at the input and output port for allowing only the RF signal to pass and blocking the DC component in the signal. The DC blocking capacitors are included inside the APM module. Therefore, C1 & C2 capacitors may not be necessary, but can be added just in case that the customer wants. The value of C1 & C2 is determined by considering the application frequency.

Recommended Soldering Reflow Process

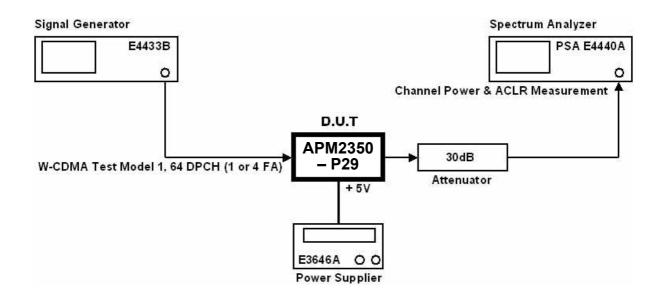




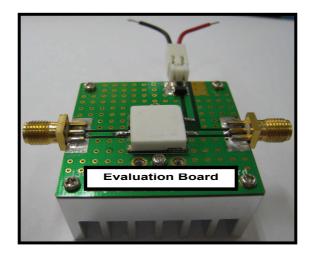


Low Noise & High OIP3 Medium Power Amplifier Module

Channel Power vs. ACLR Test Configuration



Evaluation Board attached with Heat Sink



* In order to prevent damage of D.U.T (APM-Series) from heating, you must to use a properly sized heat sink for testing a module.